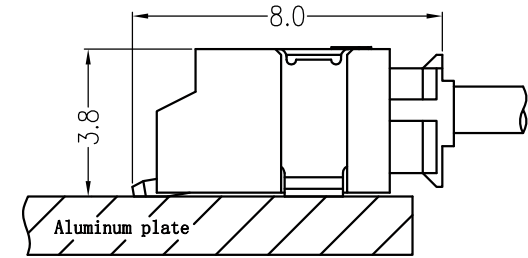
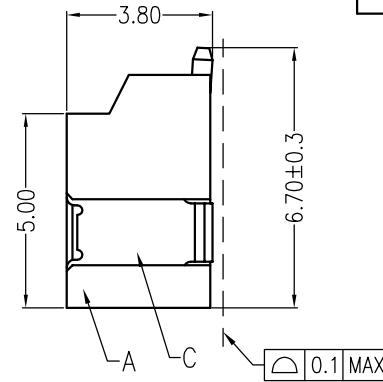
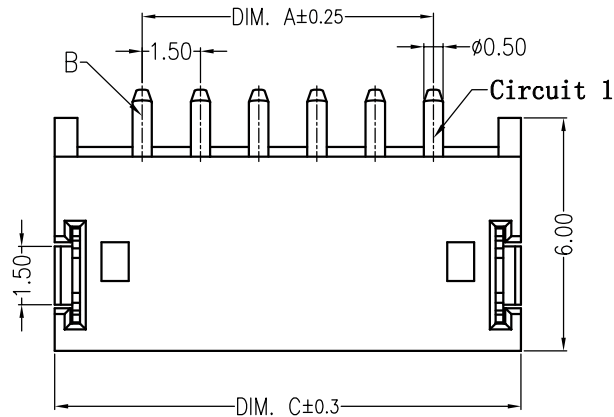


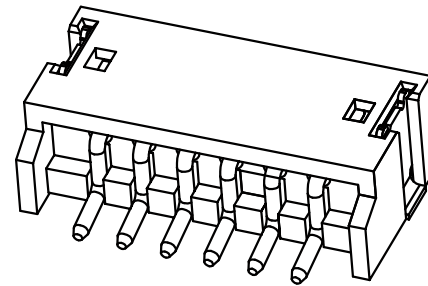
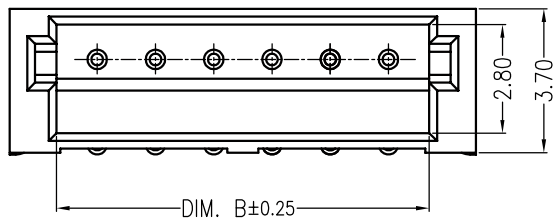
REV	ECN No.	DESCRIPTION	DESIGN	DATE
A0		Release	吴丹平	2016.05.05



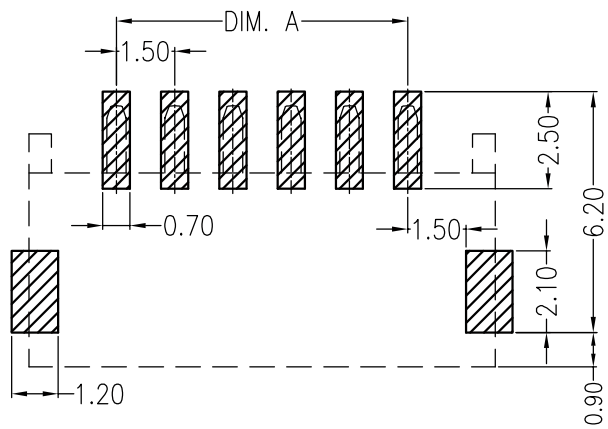
Assembly Layout

主要技术参数 Main Specifications

- 线 数 (Poles): 02 to 16
- 接触电阻 (Contact resistance): $\leq 20m\Omega$
- 绝缘电阻 (Insulation resistance): $\geq 500M\Omega$
- 额定电压 (Rated voltage): 125V AC DC
- 额定电流 (Rated current): 1.0A AC DC
- 耐 电压 (Withstand Voltage): 500V AC/minute
- 温度范围 (Temperature Range): $-25^{\circ}C \sim +105^{\circ}C$



Circuits	Dimensions (mm)		
	DIM. A	DIM. B	DIM. C
02	1.50	3.60	6.00
03	3.00	5.10	7.50
04	4.50	6.60	9.00
05	6.00	8.10	10.50
06	7.50	9.60	12.00
07	9.00	11.10	13.50
08	10.50	12.60	15.00
09	12.00	14.10	16.50
10	13.50	15.60	18.00
11	15.00	17.10	19.50
12	16.50	18.60	21.00
13	18.00	20.10	22.50
14	19.50	21.60	24.00
15	21.00	23.10	25.50
16	22.50	24.60	27.00



SUGGESTED PCB LAYOUT

ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
C	SOLDER TAB	2 PCS	PhosphorBronze	Sn-plated
B	CONTACT	2~16 PCS	Brass	Sn-plated
A	PEDESTAL	1 PCS	LCP	UL 94V-0, COLOR:BEIGE

LEDsconn			TITLE: 1.5mmPITCH 90°WAFER SMT TYPE	
X.±0.5	X.±5'	USE: CUSTOMER	PART NO.:	
.X±0.3	.X±2'			
.XX±0.25	.XX±1'	APPD: 邵敬和	DWG NO.:	
--	--	CHKD: 田峰		
UNITS: mm		DR: 吴丹平	SCALE 1 : 1	SHEET 1 / 1